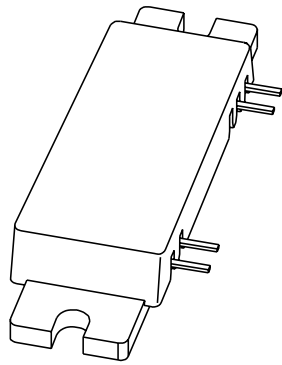


# DATA SHEET



## **BGY1816** UHF amplifier module

Product specification  
Supersedes data of 1998 May 27

2000 Oct 17

# UHF amplifier module

# BGY1816

### FEATURES

- 26 V nominal supply voltage
- 16 W output power into a load of 50 Ω with an RF drive power of ≤63 mW.

### APPLICATIONS

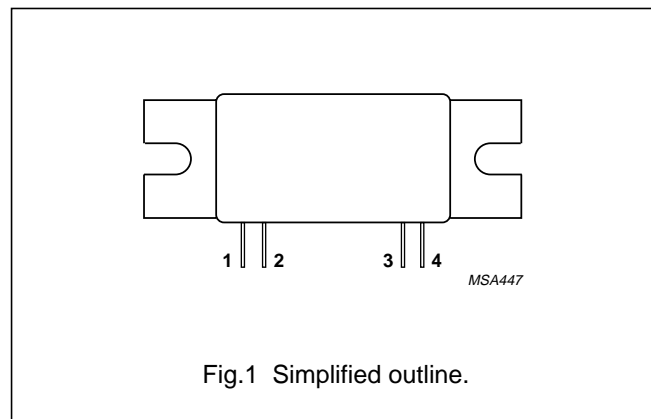
- Base station transmitting equipment operating in the 1805 to 1880 MHz frequency band.

### DESCRIPTION

The BGY1816 is a three-stage UHF amplifier module in a SOT365A package with a plastic cap. It consists of three NPN silicon planar transistor dies mounted together with matching and bias circuit components on a metallized ceramic AlN substrate.

### PINNING - SOT365A

PIN	DESCRIPTION
1	RF input
2	V <sub>S1</sub>
3	V <sub>S2</sub>
4	RF output
Flange	ground



### QUICK REFERENCE DATA

RF performance at T<sub>mb</sub> = 25 °C.

MODE OF OPERATION	f (MHz)	V <sub>S1</sub> (V)	V <sub>S2</sub> (V)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η (%)	Z <sub>S</sub> ; Z <sub>L</sub> (Ω)
CW	1805 to 1880	5	26	≥16	≥24	≥30	50

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>S1</sub>	DC supply voltage		4.5	5.5	V
V <sub>S2</sub>	DC supply voltage		–	28	V
P <sub>D</sub>	input drive power		–	120	mW
P <sub>L</sub>	load power	T <sub>mb</sub> = 25 °C	–	20	W
T <sub>stg</sub>	storage temperature		–30	+100	°C
T <sub>mb</sub>	operating mounting base temperature		–10	+90	°C

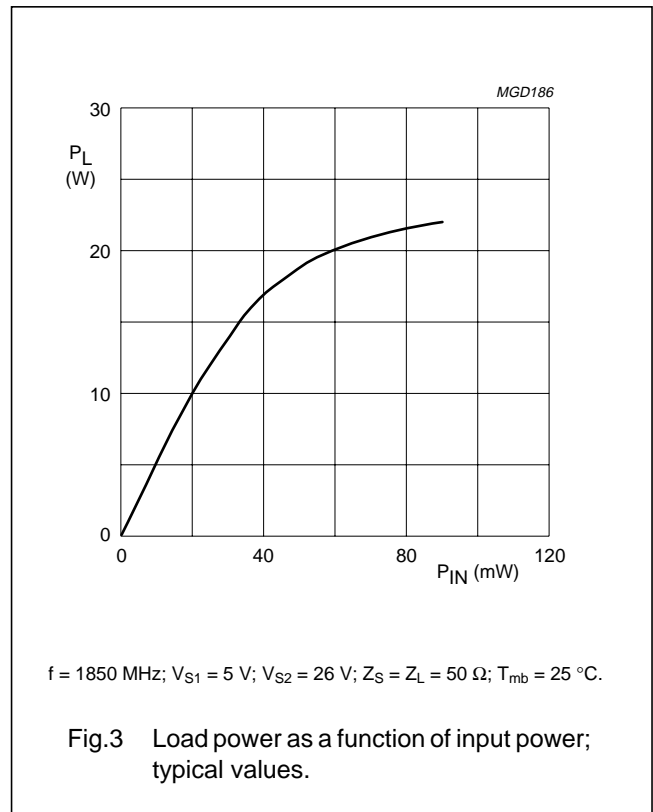
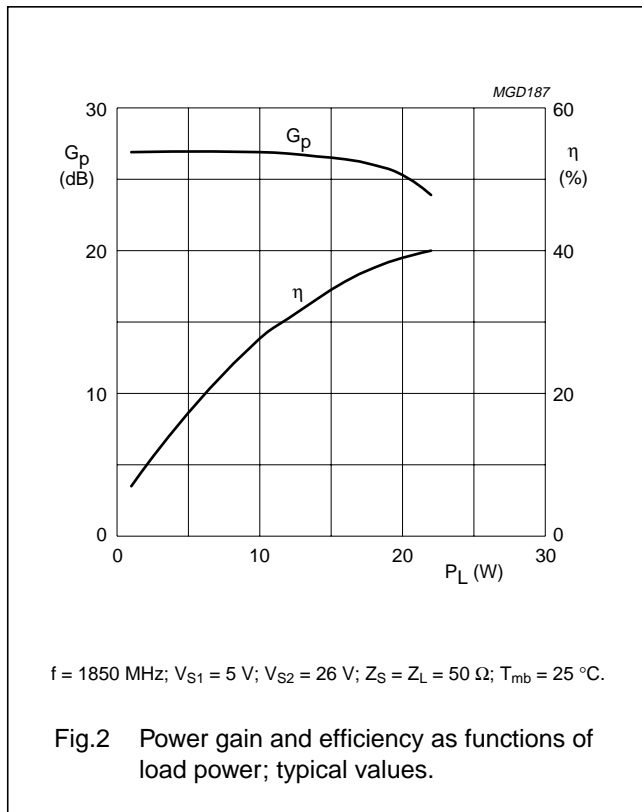
UHF amplifier module

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**CHARACTERISTICS**

$T_{mb} = 25\text{ }^{\circ}\text{C}$ ;  $V_{S1} = 5\text{ V}$ ;  $V_{S2} = 26\text{ V}$ ;  $P_L = 16\text{ W}$ ;  $Z_S = Z_L = 50\text{ }\Omega$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f	frequency		1805	–	1880	MHz
$I_{S1}$	supply current		–	80	–	mA
$I_{S2}$	supply current	$P_D < -60\text{ dBm}$	–	430	–	mA
$P_L$	load power	$P_D < 63\text{ mW}$	16	–	–	W
$G_p$	power gain		24	–	28	dB
$\eta$	efficiency		30	–	–	%
$H_2$	second harmonic		–	–	-35	dBc
$H_3$	third harmonic		–	–	-40	dBc
$VSWR_{in}$	input VSWR		–	–	1.6 : 1	
	stability	$VSWR \leq 2 : 1$ through all phases; $P_L \leq 16\text{ W}$ ; $V_{S2} = 25\text{ to }27\text{ V}$	–	–	-60	dBc
	reverse intermodulation	$P_{carrier} = 16\text{ W}$ ; $P_{reverse} = -40\text{ dBc}$ ; $f_i = f_c \pm 200\text{ kHz}$	–	–	-53	dBc
B	AM bandwidth	corner frequency = 3 dB; $P_{carrier} = 16\text{ W}$ ; modulation = 20%	2	–	–	MHz
	ruggedness	$VSWR \leq 5 : 1$ through all phases	no degradation			



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APPLICATION INFORMATION

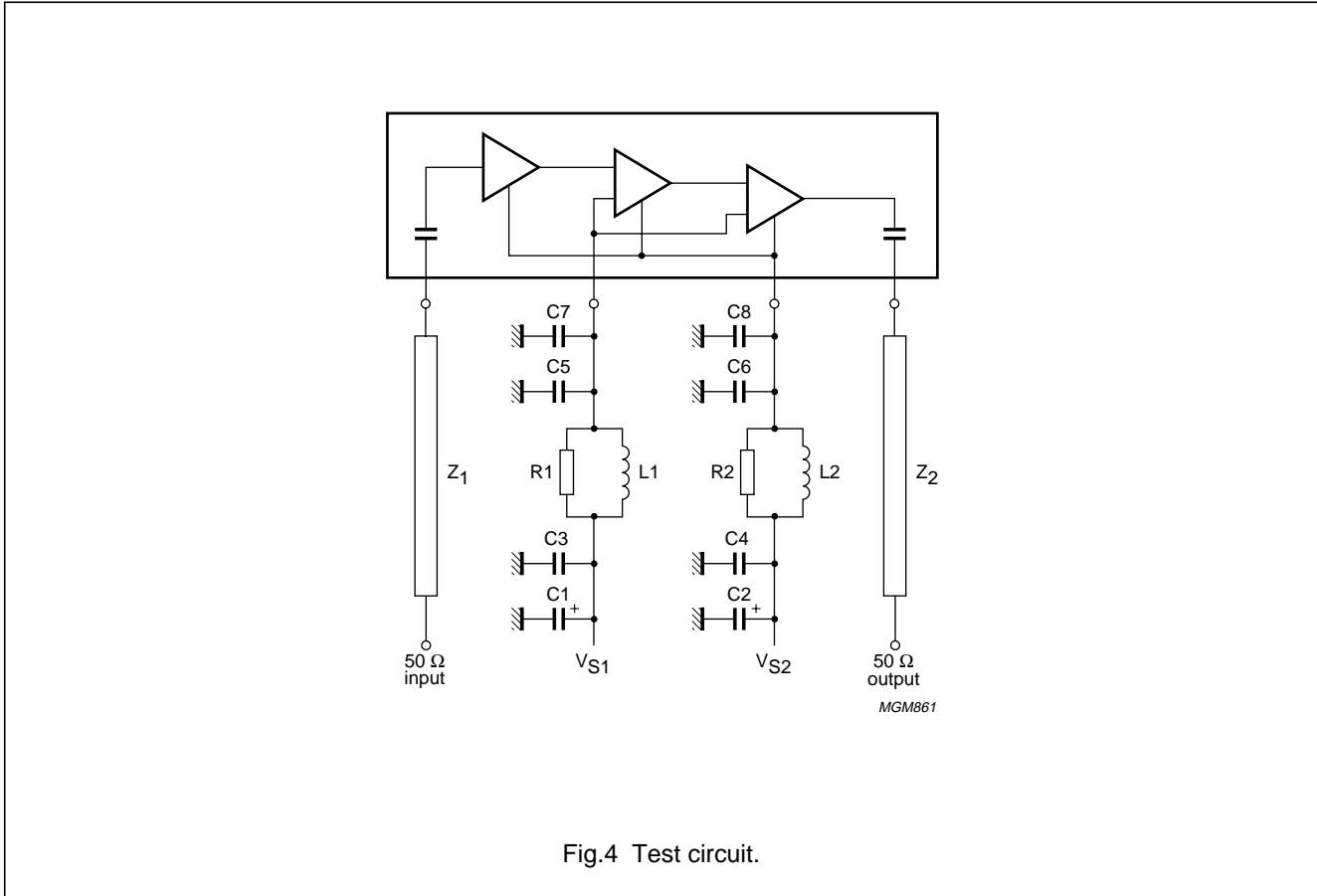


Fig.4 Test circuit.

List of components (see Figs 4 and 5)

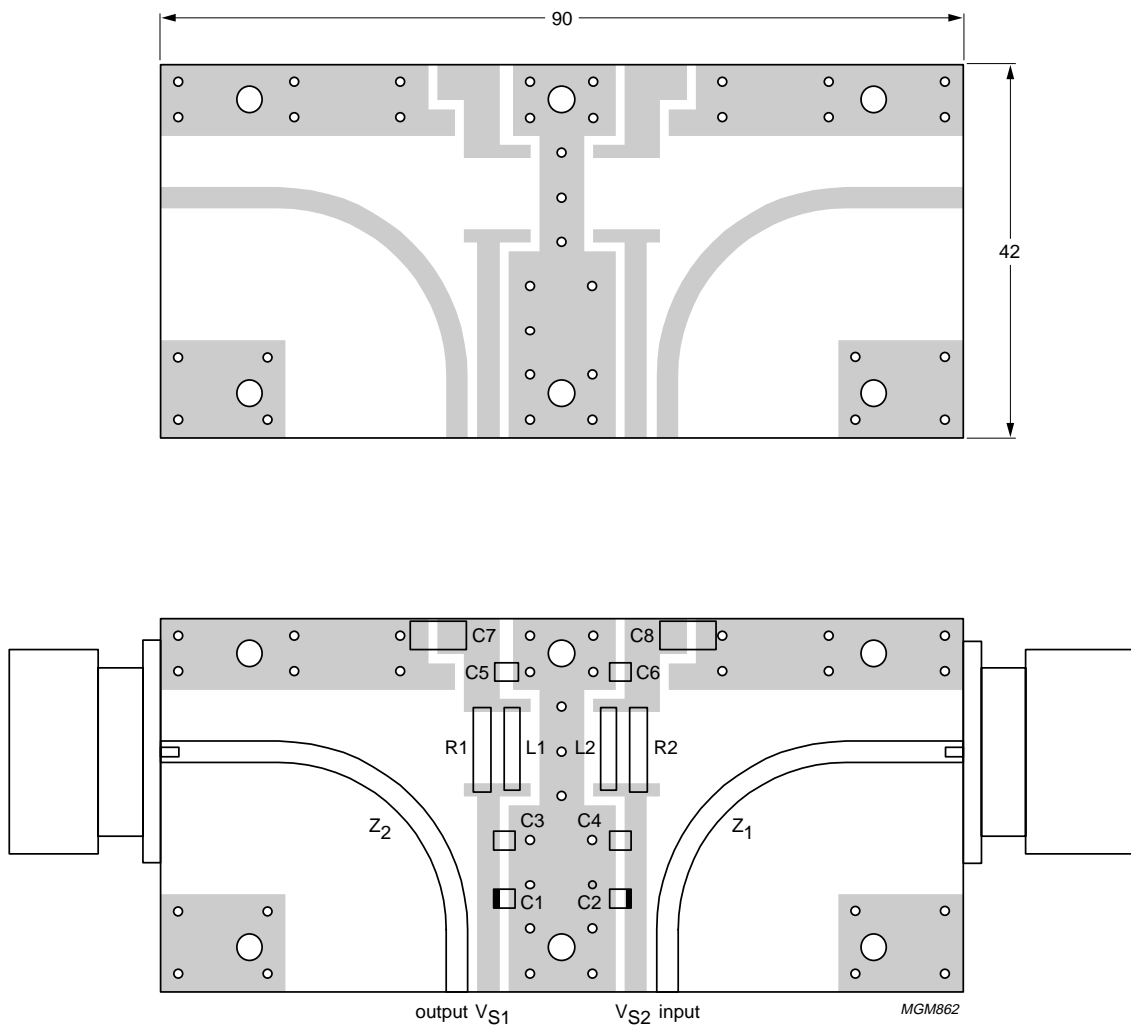
COMPONENT	DESCRIPTION	VALUE	CATALOGUE NO.
C1, C2	electrolytic capacitor	10 $\mu$ F; 35 V	
C3, C4	multilayer ceramic chip capacitor	10 nF; 50 V	
C5, C6	multilayer ceramic chip capacitor	100 pF; 50 V	
C7, C8	multilayer ceramic chip capacitor	10 pF; 50 V	
L1, L2	Grade 4S2 Ferroxcube bead		4330 030 36300
R1, R2	metal film resistor	10 $\Omega$ ; 0.4 W	2322 195 13109
Z1, Z2	stripline: note 1	50 $\Omega$	

Note

1. The striplines are on a double copper-clad printed-circuit board (RO5880) with  $\epsilon_r = 2.2$  and thickness = 0.79 mm.

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Dimensions in mm.

Fig.5 Printed-circuit board component layout.

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## UHF amplifier module

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### **MOUNTING RECOMMENDATIONS**

To ensure a good thermal contact and to prevent mechanical stress when bolted down, the flatness of the mounting base is designed to be typically better than 0.1 mm. The mounting area of the heatsink should be flat and free from burrs and loose particles. The heatsink should be rigid and not prone to bowing under thermal cycling conditions. The thickness of a solid heatsink should be not less than 5 mm to ensure a rigid assembly.

A thin, even layer of thermal compound should be applied between the mounting base and the heatsink to achieve the best possible thermal contact resistance. Excessive use of thermal compound will result in an increase in thermal resistance and possible bowing of the mounting base; too little will also result in poor thermal conduction.

The module should be mounted to the heatsink using 3 mm bolts with flat washers. The bolts should first be tightened to “finger tight” and then further tightened in alternating steps to a maximum torque of 0.4 to 0.6 Nm.

Once mounted on the heatsink, the module leads can be soldered to the printed-circuit board. A soldering iron may be used up to a temperature of 250 °C for a maximum of 10 seconds at a distance of 2 mm from the plastic cap.

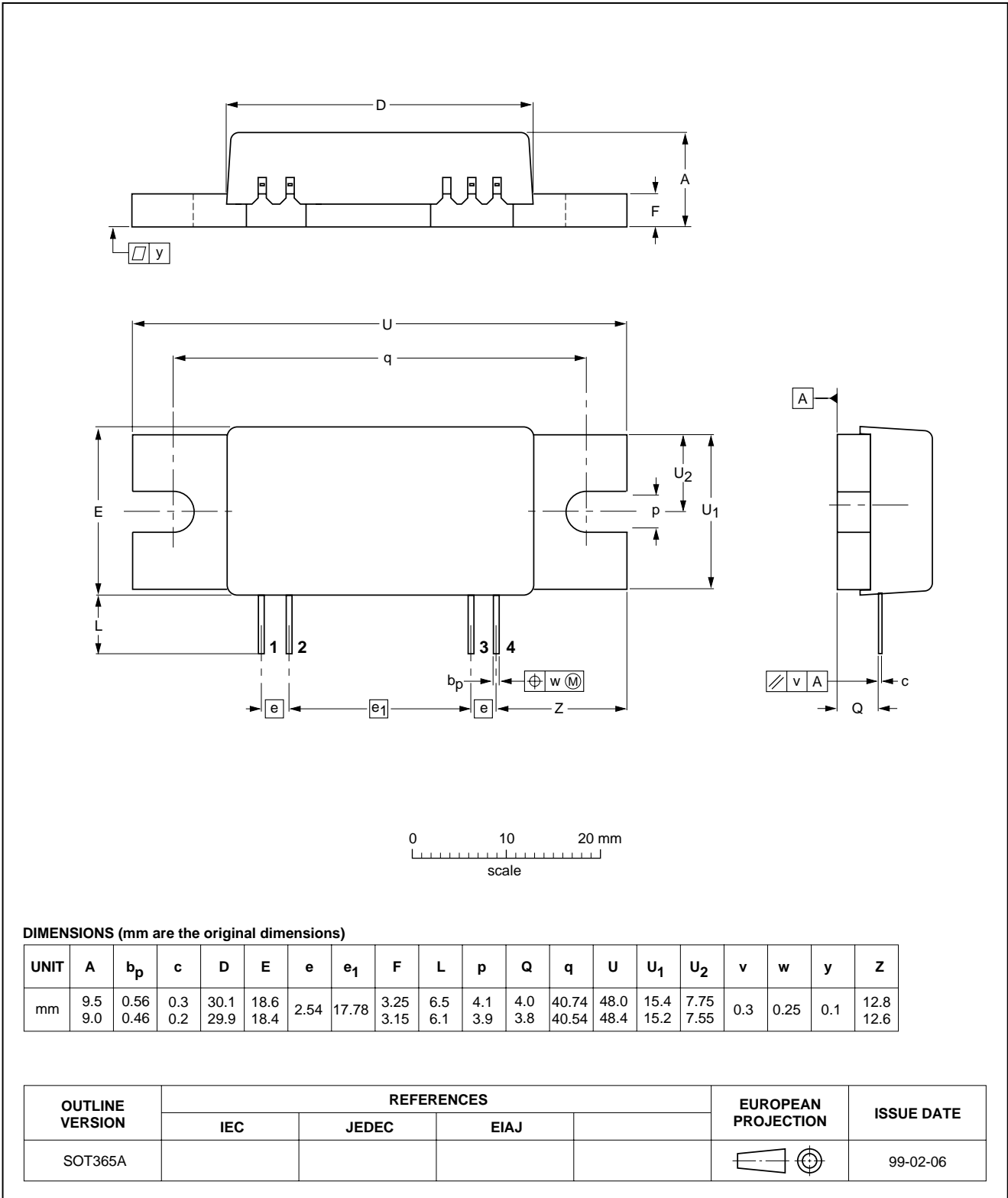
ESD precautions must be taken to protect the device from electrostatic damage.

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PACKAGE OUTLINE

Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 4 in-line leads SOT365A



## UHF amplifier module

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## DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS <sup>(1)</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

## Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

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**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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**NOTES**

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**NOTES**

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**NOTES**

# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 3 Figtree Drive, HOMEBUSH, NSW 2140,  
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

**Austria:** Computerstr. 6, A-1101 WIEN, P.O. Box 213,  
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

**Belgium:** see The Netherlands

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**Bulgaria:** Philips Bulgaria Ltd., Energoproject, 15th floor,  
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**Denmark:** Sydhavnsgade 23, 1780 COPENHAGEN V,  
Tel. +45 33 29 3333, Fax. +45 33 29 3905

**Finland:** Sinikalliontie 3, FIN-02630 ESPOO,  
Tel. +358 9 615 800, Fax. +358 9 6158 0920

**France:** 51 Rue Carnot, BP317, 92156 SURESNES Cedex,  
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

**Germany:** Hammerbrookstraße 69, D-20097 HAMBURG,  
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Band Box Building, 2nd floor,  
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,  
Tel. +91 22 493 8541, Fax. +91 22 493 0966

**Indonesia:** PT Philips Development Corporation, Semiconductors Division,  
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,  
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

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Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,  
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),  
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**Japan:** Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,  
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**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
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**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
Tel. +60 3 750 5214, Fax. +60 3 757 4880

**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
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Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
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**Poland:** Al.Jerozolimskie 195 B, 02-222 WARSAW,  
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Tel. +27 11 471 5401, Fax. +27 11 471 5398

**South America:** Al. Vicente Pinzon, 173, 6th floor,  
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**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
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TAIPEI, Taiwan Tel. +886 2 2134 2451, Fax. +886 2 2134 2874

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**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

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Tel. +381 11 3341 299, Fax.+381 11 3342 553

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